

#48/100E
5/13/02

Attorney Docket No.: 94-36-3-US-D1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Werenicz et al.

Art Unit: 1733

Serial No.: 09/057,406

Examiner: J. Aftergut

Filed: April 8, 1998

Title: METHOD FOR PRODUCING A CONTINUOUS THERMOPLASTIC
COATING

Assistant Commissioner for Patents

Washington, D.C. 20231

BOX AMENDMENT

RESPONSE

In response to the outstanding Office action dated February 4, 2002, Applicants submit the following remarks.

Remarks

Claims 3-6, 8, 10-12, 33, 35, 36, 39-42, 44, and 46-48 stand rejected under 35 U.S.C. § 103 over Sanftleben et al. (U.S. 5,510,138) in view of Boger et al. (U.S. 5,409,733).

Sanftleben et al. disclose conformal coating materials for forming a protective conformal coating on the surface of an electronic assembly, e.g., a filled printed circuit board. The conformal coating materials of Sanftleben et al. include hot melt compositions that are either nonreactive, i.e., can be remelted after solidifying, or reactive, i.e., curable.

Boger et al. disclose an apparatus for applying a conformal coating on a substrate. Boger et al. disclose that the prior art included five principal methods of applying coatings of moisture proof insulators to printed circuit boards. One of the five methods is a slit die method in which the moisture proof insulator is pressurized and extruded from a slit die to eject a film for coating the printed circuit board surface.

Claim 10, the first independent claim, is directed to a method of forming a continuous film layer of a thermoplastic composition onto a substrate. The method includes providing a molten thermoplastic composition, advancing a substrate along a

CERTIFICATE OF TRANSMISSION

I hereby certify under 37 CFR §1.8(a) that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office. Fax No. (703) 872-9310 on May 9, 2002

Signature

Allison Johnson

Typed or Printed Name of Person Signing Certificate